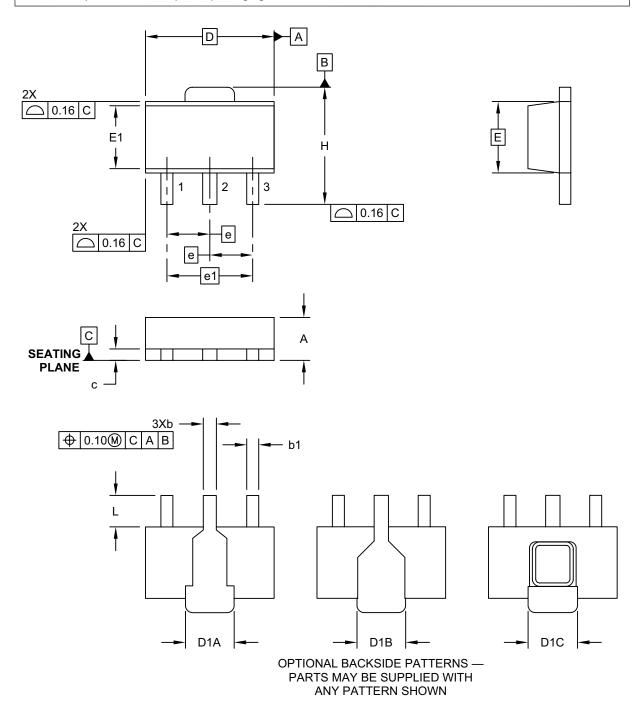


3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

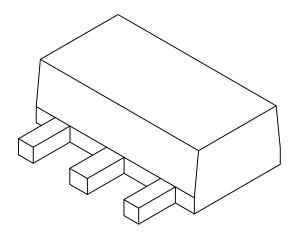


Microchip Technology Drawing C04-029C Sheet 1 of 2



3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	3		
Pitch	е	1.50 BSC		
Outside Lead Pitch	e1	3.00 BSC		
Overall Height	Α	1.40	1.50	1.60
Overall Width	Н	3.94	4.10	4.25
Molded Package Width at Base	Е	2.50 BSC		
Molded Package Width at Top	E1	2.13	2.20	2.29
Overall Length	D	4.50 BSC		
Tab Length (Option A)	D1A	1.63	1.73	1.83
Tab Length (Option B)	D1B	1.40	1.60	1.75
Tab Length (Option C)	D1C	1.62	1.73	1.83
Foot Length	L	0.79	1.10	1.20
Lead Thickness	С	0.35	0.40	0.44
Lead 2 Width	b	0.41	0.50	0.56
Leads 1 & 3 Width	b1	0.36	0.42	0.48

Notes:

- 1. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M

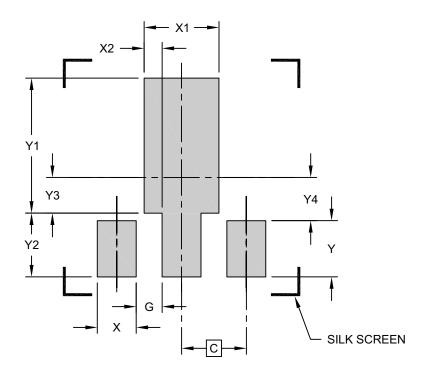
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-029C Sheet 2 of 2



3-Lead Plastic Small Outline Transistor (MB) - [SOT-89]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units	MILLIMETERS				
Dimension Limits	MIN	NOM	MAX		
С	1.50 (BSC)				
X (3 PLACES)		0.900			
X1		1.733			
X2 (2 PLACES)		0.416			
G (2 PLACES)		0.600			
Y (2 PLACES)		1.300			
Y1		3.125			
Y2		1.475			
Y3		0.825			
Y4		1.000			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2029C